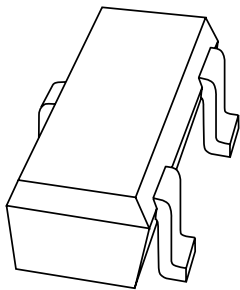


# DATA SHEET



**2PD602A**

**NPN general purpose transistor**

Product data sheet  
Supersedes data of 1997 Jun 20

1999 Apr 23

# NPN general purpose transistor

# 2PD602A

### FEATURES

- High current (max. 500 mA)
- Low voltage (max. 50 V).

### APPLICATIONS

- General purpose switching and amplification.

### DESCRIPTION

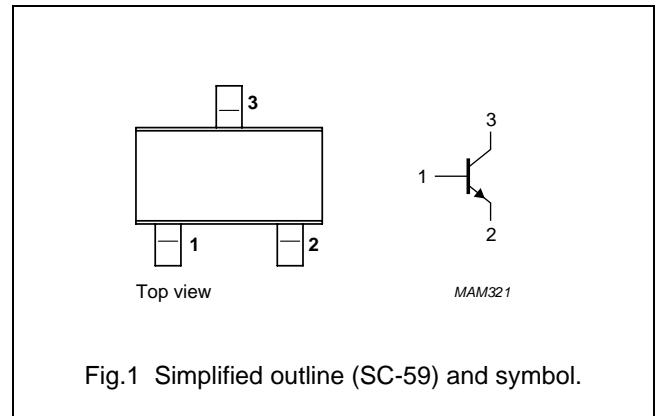
NPN transistor in an SC-59 plastic package.  
PNP complement: 2PB710A.

### MARKING

TYPE NUMBER	MARKING CODE
2PD602AQ	XQ
2PD602AR	XR
2PD602AS	XS

### PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	60	V
$V_{CEO}$	collector-emitter voltage	open base	–	50	V
$V_{EBO}$	emitter-base voltage	open collector	–	5	V
$I_C$	collector current (DC)		–	500	mA
$I_{CM}$	peak collector current		–	1	A
$I_{BM}$	peak base current		–	200	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ }^\circ\text{C}$ ; note 1	–	250	mW
$T_{stg}$	storage temperature		–65	+150	$^\circ\text{C}$
$T_j$	junction temperature		–	150	$^\circ\text{C}$
$T_{amb}$	operating ambient temperature		–65	+150	$^\circ\text{C}$

### Note

1. Transistor mounted on an FR4 printed-circuit board.

## NPN general purpose transistor

2PD602A

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient	note 1	500	K/W

## Note

1. Transistor mounted on an FR4 printed-circuit board.

## CHARACTERISTICS

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector cut-off current	$I_E = 0; V_{CB} = 60\text{ V}$	–	10	nA
		$I_E = 0; V_{CB} = 60\text{ V}; T_j = 150\text{ °C}$	–	5	$\mu\text{A}$
$I_{EBO}$	emitter cut-off current	$I_C = 0; V_{EB} = 4\text{ V}$	–	10	nA
$h_{FE}$	DC current gain	$I_C = 150\text{ mA}; V_{CE} = 10\text{ V};$ note 1	85	170	
	2PD602AQ				
2PD602AR					
	2PD602AS	170	340		
	DC current gain	$I_C = 500\text{ mA}; V_{CE} = 10\text{ V};$ note 1	40	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = 300\text{ mA}; I_B = 30\text{ mA};$ note 1	–	600	mV
$C_c$	collector capacitance	$I_E = i_e = 0; V_{CB} = 10\text{ V}; f = 1\text{ MHz}$	–	15	pF
$f_T$	transition frequency	$I_C = 50\text{ mA}; V_{CE} = 10\text{ V};$ $f = 100\text{ MHz};$ note 1	140	–	MHz
	2PD602AQ				
	2PD602AR				
	2PD602AS	180	–	MHz	

## Note

1. Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02.$

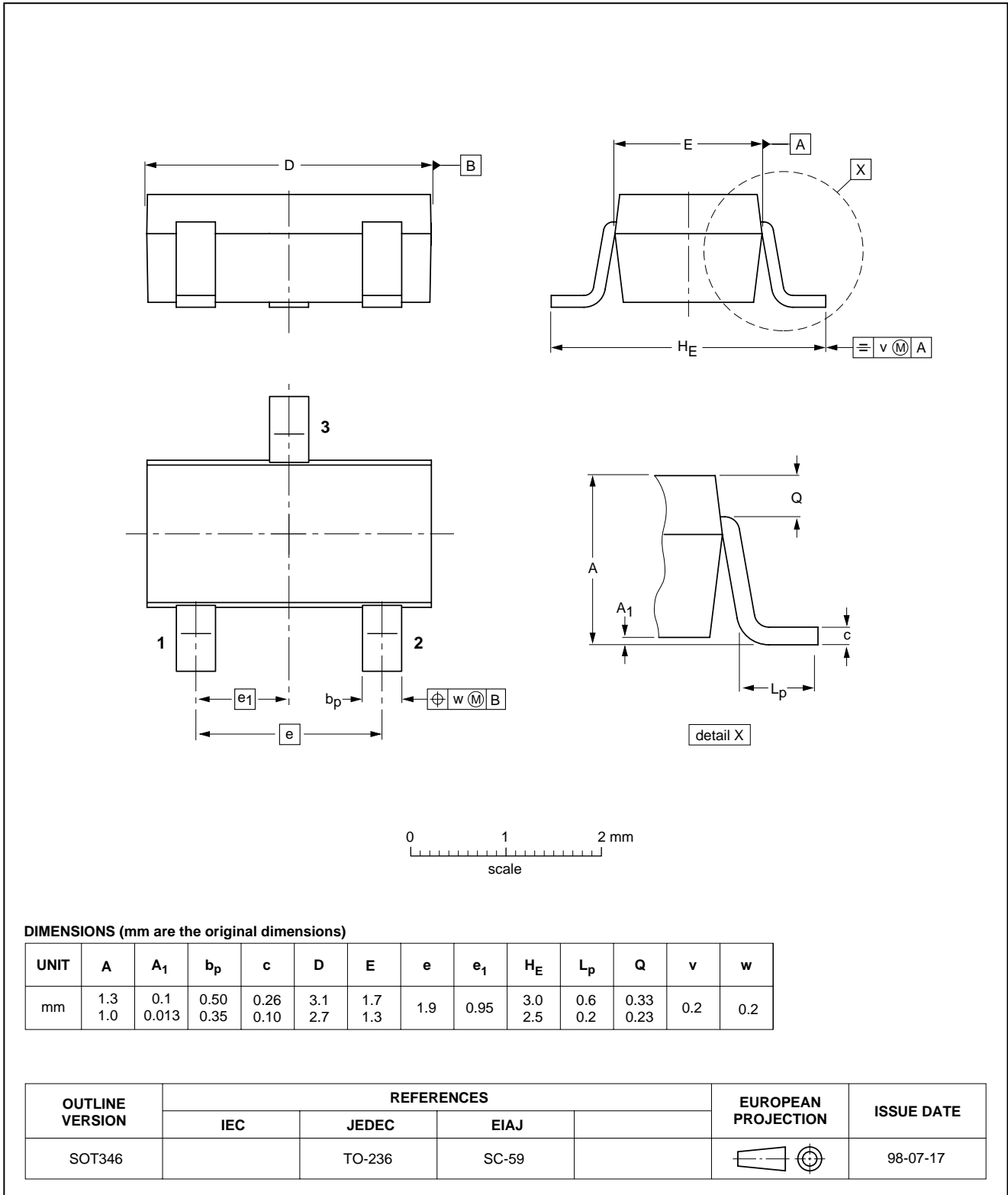
NPN general purpose transistor

2PD602A

PACKAGE OUTLINE

Plastic surface mounted package; 3 leads

SOT346



## NPN general purpose transistor

2PD602A

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## **Contact information**

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